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Attorney Docket No. 108298742US Express Mail No. EV758925803US Disclosure No. 03-0599.00/US Docket No. AMENDMENT TRANSMITTAL LETTER 108298742US Filing Date Examiner Art Unit Application No. H. Weiss 2814 10/713,878-Conf. #1111 November 13, 2003 Applicant(s): Rigg et al. MICROELECTRONIC DEVICES, METHODS FOR FORMING VIAS IN Invention: MICROELECTRONIC DEVICES, AND METHODS FOR PACKAGING MICROELECTRONIC **DEVICES** TO THE COMMISSIONER FOR PATENTS Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below. **CLAIMS AS AMENDED** Claims Highest Number Number Remaining **Extra Claims** After Previously Amendment Paid Present Rate 26 43 Х **Total Claims** Independent 6 Х Claims Multiple Dependent Claims (check if applicable) Other fee (please specify): 0.00 TOTAL ADDITIONAL FEE FOR THIS AMENDMENT: Small Entity x Large Entity x | No additional fee is required for this amendment. in the amount of \$ Please charge Deposit Account No. A duplicate copy of this sheet is enclosed. A check in the amount of \$ to cover the filing fee is enclosed. Payment by credit card. Form PTO-2038 is attached. x | The Director is hereby authorized to charge and credit Deposit Account No. as described below. x Credit any overpayment.

x Charge any attitional filing or application processing fees required under 37 CFR 1.16 and 1.17.

March 15, 2006

Dated:

Stephen E. Amett

Attorney/Agent Reg. No.: 47,392

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RESPONSE UNDER 37 C.F.R. § 1.116 EXPEDITED PROCEDURE – Art Unit 2814

CONF. No:

Attorney Docket No. 108298742US Disclosure No. 03-0599.00/US

2814

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PATENT

HOWARD WEISS



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: SIDNEY B. RIGG ET AL.

EY B. RIGG ET AL. EXAMINER: 13.878 ART UNIT:

APPLICATION No.: 10/713,878

FILED: NOVEMBER 13, 2003

FOR: MICROELECTRONIC DEVICES,

METHODS FOR FORMING VIAS IN MICROELECTRONIC DEVICES, AND

METHODS FOR PACKAGING

MICROELECTRONIC DEVICES

Amendment Under 37 C.F.R. § 1.116

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

The present communication responds to the Office Action dated December 16, 2005 in the above-identified application. Please amend the application as follows:

Amendments to the Specification begin on page 2.

Amendments to the Claims are reflected in the listing of claims beginning on page 3.